National Semiconductor is now part of

Texas Instruments.

Search <u>http://www.ti.com/</u> for the latest technical

information and details on our current products and services.

September 22, 2011



Semiconductor DS90UR903Q/DS90UR904Q

10 - 43MHz 18 Bit Color FPD-Link II Serializer and Deserializer

General Description

The DS90UR903Q/DS90UR904Q chipset offers a FPD-Link II interface with a high-speed forward channel for data transmission over a single differential pair. The Serializer/ Deserializer pair is targeted for direct connections between graphics host controller and displays modules. This chipset is ideally suited for driving video data to displays requiring 18-bit color depth (RGB666 + HS, VS, and DE). The serializer converts 21 bit data over a single high-speed serial stream. This single serial stream simplifies transferring a wide data bus over PCB traces and cable by eliminating the skew problems between parallel data and clock paths. This significantly saves system cost by narrowing data paths that in turn reduce PCB layers, cable width, and connector size and pins.

The Deserializer inputs provide equalization control to compensate for loss from the media over longer distances. Internal DC balanced encoding/decoding is used to support AC-Coupled interconnects.

The Serializer is offered in a 40-pin lead in LLP and Deserializer is offered in a 48-pin LLP packages.

Features

- 10 MHz to 43 MHz input PCLK support
- 210 Mbps to 903 Mbps data throughput
- Single differential pair interconnect
- Embedded clock with DC Balanced coding to support ACcoupled interconnects
- **Typical Application Diagram**

- Capable to drive up to 10 meters shielded twisted-pair
- I²C compatible serial interface for device configuration
- Single hardware device addressing pin
- LOCK output reporting pin to validate link integrity
- Integrated termination resistors
- 1.8V- or 3.3V-compatible parallel bus interface
- Single power supply at 1.8V
- ISO 10605 ESD and IEC 61000-4-2 ESD compliant
- Automotive grade product: AEC-Q100 Grade 2 qualified
- Temperature range -40°C to +105°C
- No reference clock required on Deserializer
- Programmable Receive Equalization
- EMI/EMC Mitigation
 - DES Programmable Spread Spectrum (SSCG) outputs
 - DES Receiver staggered outputs

Applications

- Automotive Display Systems
- Central Information Displays
 - Navigation Displays
 - Rear Seat Entertainment

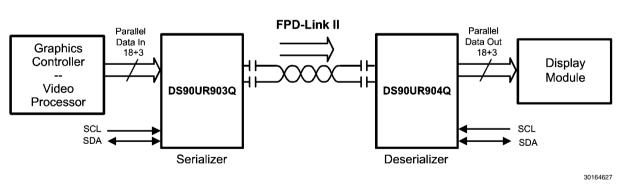
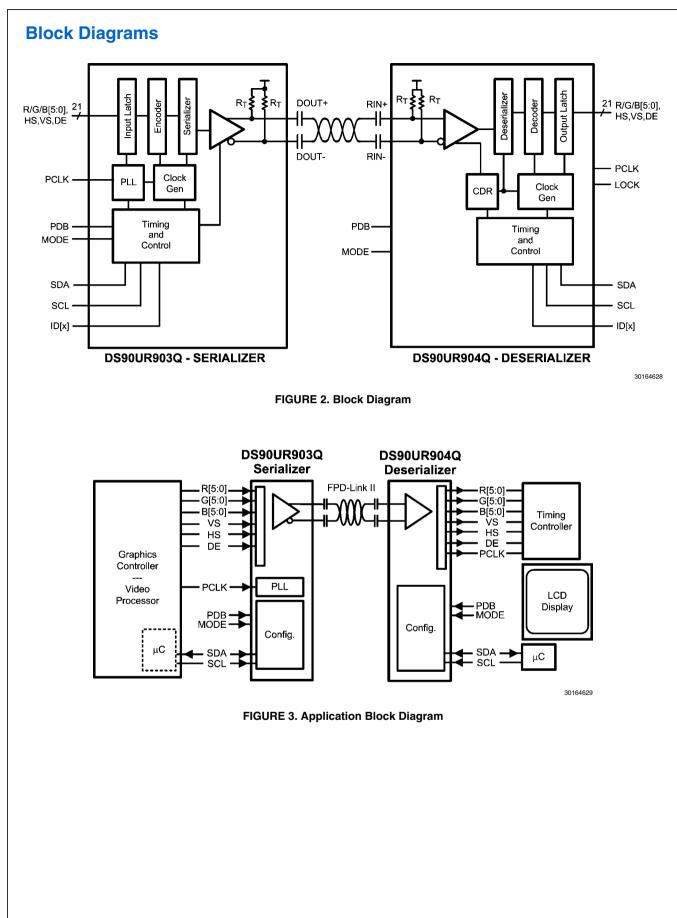


FIGURE 1. Typical Application Circuit

TRI-STATE® is a registered trademark of National Semiconductor Corporation.

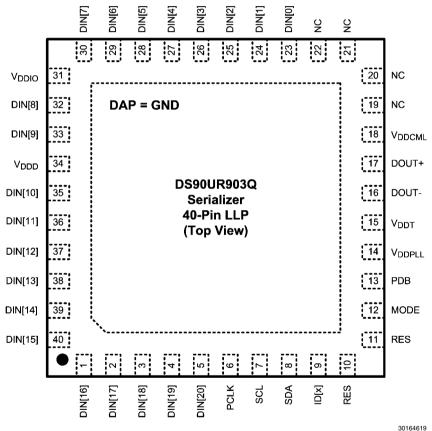


Ordering Information

NSID	Package Description	Quantity	SPEC	Package ID
DS90UR903QSQE	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	250	NOPB	SQA40A
DS90UR903QSQ	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	1000	NOPB	SQA40A
DS90UR903QSQX	40-pin LLP, 6.0 X 6.0 X 0.8 mm, 0.5 mm pitch	4500	NOPB	SQA40A
DS90UR904QSQE	48-pin LLP, 7.0 X 7.0 X 0.8 mm, 0.5 mm pitch	250	NOPB	SQA48A
DS90UR904QSQ	48-pin LLP, 7.0 X 7.0 X 0.8 mm, 0.5 mm pitch	1000	NOPB	SQA48A
DS90UR904QSQX	48-pin LLP, 7.0 X 7.0 X 0.8 mm, 0.5 mm pitch	4500	NOPB	SQA48A

Note: Automotive Grade (Q) product incorporates enhanced manufacturing and support processes for the automotive market, including defect detection methodologies. Reliability qualification is compliant with the requirements and temperature grades defined in the AEC Q100 standard. Automotive Grade products are identified with the letter Q. For more information go to http://www.national.com/automotive.

DS90UR903Q Pin Diagram

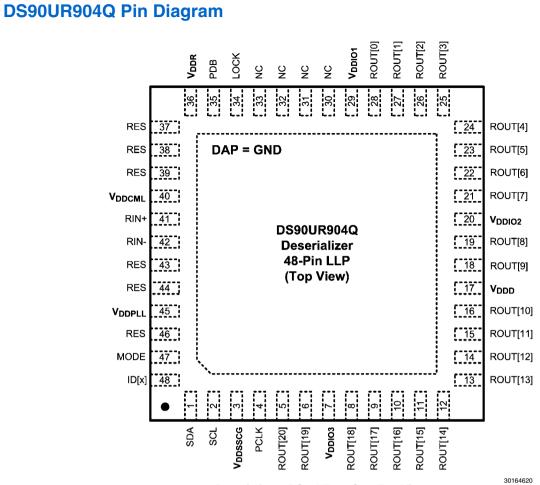


Serializer - DS90UR903Q — Top View

DS90UR903Q Serializer Pin Descriptions

Pin Name	Pin No.	I/O, Type	Description
LVCMOS PAR	ALLEL INTERFA	NCE	
DIN[20:0]	5, 4, 3, 2, 1, 40, 39, 38, 37, 36, 35, 33, 32, 30, 29, 28, 27, 26, 25, 24, 23	w/ pull down	Parallel data inputs.
PCLK	6	Input, LVCMOS w/ pull down	Pixel Clock Input Pin. Strobe edge set by TRFB control register.

ROL BUS - I ² C C	OMPATIBLE	
7	Input,	Clock line for the serial control bus communication
	Open Drain	SCL requires an external pull-up resistor to V _{DDIO} .
0	Input/Output,	Data line for the serial control bus communication
°	Open Drain	SDA requires an external pull-up resistor to V _{DDIO} .
	Input LVCMOS	I ² C Mode select
12		MODE = H,- REQUIRED . The MODE pin must be set HIGH to allow I ² C
		configuration of the serializer.
9	Innut analog	Device ID Address Select
Ŭ	input, analog	Resistor to Ground and 10 k Ω pull-up to 1.8V rail. See <i>Table 3</i>
D CONFIGURAT	ION	
		Power down Mode Input Pin.
10	Input, LVCMOS	PDB = H, Serializer is enabled and is ON.
13	w/ pull down	PDB = L, Serailizer is in Power Down mode. When the Serializer is in Power Down
		the PLL is shutdown, and IDD is minimized. Programmed control register data are NOT retained and reset to default values
	Input LVCMOS	Reserved.
10, 11		This pin MUST be tied LOW.
22, 21, 20, 19		No Connect
ITERFACE		
17	Output, CML	Non-inverting differential output. The interconnect must be AC Coupled with a 100
17		nF capacitor.
16	Output, CML	Inverting differential output. The interconnect must be AC Coupled with a 100 nF
		capacitor.
GROUND		
14	Power, Analog	PLL Power, 1.8V ±5%
15	Power, Analog	Tx Analog Power, 1.8V ±5%
18	Power, Analog	CML Power, 1.8V ±5%
34	Power, Digital	Digital Power, 1.8V ±5%
21	Power, Digital	Power for I/O stage. The single-ended inputs and SDA, SCL are powered from
		V_{DDIO} . V_{DDIO} can be connected to a 1.8V ±5% or 3.3V ±10%
	Ground, DAP	DAP must be grounded. DAP is the large metal contact at the bottom side, located
DAP		at the center of the LLP package. Connected to the ground plane (GND) with at least 16 vias.
	7 8 12 9 CONFIGURAT 13 10, 11 22, 21, 20, 19 ITERFACE 17 16 GROUND 14 15 18 34 31	7Open Drain8Input/Output, Open Drain12Input, LVCMOS w/ pull down9Input, analogD CONFIGURATION13Input, LVCMOS w/ pull down13Input, LVCMOS





DS90UR904Q Deserializer Pin Descriptions

Pin Name	Pin No.	I/O, Type	Description	
VCMOS PAR	ALLEL INTERFA	CE		
ROUT[20:0]	5, 6, 8, 9, 10,	Outputs,	Parallel data outputs.	
	11, 12, 13, 14,	LVCMOS		
	15, 16, 18, 19,			
	21, 22, 23, 24,			
	25, 26, 27, 28			
	4	Output,	Pixel Clock Output Pin.	
PCLK	4	LVCMOS	Strobe edge set by RRFB control register.	

		Input	Clock line for the serial control bus communication
SCL	2	Input,	
		Open Drain	SCL requires an external pull-up resistor to V _{DDIO} .
SDA	1	Input/Output,	Data line for the serial control bus communication
		Open Drain	SDA requires an external pull-up resistor to V _{DDIO} .
			I ² C Mode select
MODE	47	Input, LVCMOS	MODE = H -REQUIRED. The MODE pin must be set HIGH to allow I ² C configuration
NODL	47	w/ pull up	of the deserializer.
	48	Input, analog	Device ID Address Select
ID[x]	40	input, analog	Resistor to Ground and 10 k Ω pull-up to 1.8V rail. See <i>Table 4</i>
CONTROL	AND CONFIGURAT	ION	
			Power down Mode Input Pin.
		Input, LVCMOS w/ pull down	PDB = H, Deserializer is enabled and is ON.
PDB	35		PDB = L, Deserializer is in Power Down mode. When the Deserializer is in Power
			Down. Programmed control register data are NOT retained and reset to default
			values.
			LOCK Status Output Pin.
	34	Output,	LOCK = H, PLL is Locked, outputs are active
LOCK	34	LVCMOS	LOCK = L, PLL is unlocked, ROUT and PCLK output states are controlled by
			OSS_SEL control register. May be used as Link Status.
			Reserved.
DE0	37, 38, 39, 43,		Pin 46: This pin MUST be tied LOW.
RES	44, 46	-	Pin 37, 43, 44: Leave pin open.
			Pins 38, 39: Route to test point or leave open if unused.
NC	30, 31, 32, 33		No Connect

FPD-LINK II INTERFACE

RIN+	41	Input, CML	Noninverting differential input. The interconnect must be AC Coupled with a 100 nF capacitor.
RIN-	42	Inputt, CML	Inverting differential input. The interconnect must be AC Coupled with a 100 nF capacitor.

Pin Name	Pin No.	I/O, Type	Description
POWER AND O	ROUND		
VDDSSCG	3	Power, Digital	SSCG Power, 1.8V ±5% Power supply must be connected regardless if SSCG function is in operation.
VDDIO1/2/3	29, 20, 7	Power, Digital	LVCMOS I/O Buffer Power, The single-ended outputs and control input are powered from V _{DDIO} . V _{DDIO} can be connected to a 1.8V \pm 5% or 3.3V \pm 10%
VDDD	17	Power, Digital	Digital Core Power, 1.8V ±5%
VDDR	36	Power, Analog	Rx Analog Power, 1.8V ±5%
VDDCML	40	Power, Analog	1.8V ±5%
VDDPLL	45	Power, Analog	PLL Power, 1.8V ±5%
VSS	DAP	Ground, DAP	DAP must be grounded. DAP is the large metal contact at the bottom side, located at the center of the LLP package. Connected to the ground plane (GND) with at least 16 vias.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage – V _{DDn} (1.8V)	-0.3V to +2.5V
Supply Voltage – V _{DDIO}	-0.3V to +4.0V
LVCMOS Input Voltage I/O	
Voltage	-0.3V to + (VDDIO + 0.3V)
CML Driver I/O Voltage (V _{DD})	–0.3V to +(V _{DD} + 0.3V)
CML Receiver I/O Voltage	
(V _{DD})	–0.3V to (V _{DD} + 0.3V)
Junction Temperature	+150°C
Storage Temperature	–65°C to +150°C
Maximum Package Power	
Dissipation Capacity Package	$1/\theta_{JA}$ °C/W above +25°
Package Derating:	
DS90UR903Q 40L LLP	
θ _{JA}	30.7 °C/W
(based on 16 thermal vias)	
θ _{JC}	6.8 °C/W
(based on 16 thermal vias)	
DS90UR904Q 48L LLP	
θ _{JA}	26.9 °C/W
(based on 16 thermal vias)	
θ _{JC}	4.4 °C/W
(based on 16 thermal vias)	
ESD Rating (IEC 61000-4-2)	R _D = 330Ω, C _S = 150pF
Air Discharge	≥±25 kV
(DOUT+, DOUT-, RIN+, RIN-)	2±23 KV
Contact Discharge	≥±10 kV
(DOUT+, DOUT-, RIN+, RIN-)	
ESD Rating (ISO10605)	R _D = 330Ω, C _S = 150/330pF

ESD Rating (ISO10605)	$R_{D} = 2K\Omega, C_{S} = 150/330pF$
Air Discharge (DOUT+, DOUT-, RIN+, RIN-)	≥±15 kV
Contact Discharge (DOUT+, DOUT-, RIN+, RIN-)	≥±10 kV
ESD Rating (HBM)	≥±8 kV
ESD Rating (CDM)	≥±1 kV
ESD Rating (MM)	≥±250 V

For soldering specifications: see product folder at www.national.com and www.national.com/ms/MS/MS-SOLDERING.pdf

Recommended Operating Conditions

	Min	Nom	Max	Units
Supply Voltage	1.71	1.8	1.89	V
(V _{DDn})				
LVCMOS Supply	1.71	1.8	1.89	V
Voltage (V _{DDIO}) OR				
LVCMOS Supply	3.0	3.3	3.6	V
Voltage (V _{DDIO})				
Supply Noise				
V _{DDn} (1.8V)			25	mVp-p
V _{DDIO} (1.8V)			25	mVp-p
V _{DDIO} (3.3V)			50	mVp-p
Operating Free Air	-40	+25	+105	°C
Temperature (T _A)	40	120	1100	Ū.
PCLK Clock	10		43	MHz
Frequency				

Electrical Characteristics (Note 2, Note 3, Note 4)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
LVCMOS	DC SPECIFICATIONS 3.3V I/C	O (SER INPUTS, DES OUTPUTS, CO	NTROL INPUTS AND	OUTPUTS	5)	
V _{IH}	High Level Input Voltage	V _{IN} = 3.0V to 3.6V	2.0		V _{IN}	V
V _{IL}	Low Level Input Voltage	V _{IN} = 3.0V to 3.6V	GND		0.8	V
I _{IN}	Input Current	V _{IN} = 0V or 3.6V V _{IN} = 3.0V to 3.6V	-20	±1	+20	μA
V _{OH}	High Level Output Voltage	$V_{DDIO} = 3.0V$ to $3.6V$ $I_{OH} = -4$ mA	2.4		V _{DDIO}	v
V _{OL}	Low Level Output Voltage	$V_{DDIO} = 3.0V$ to $3.6V$ $I_{OL} = +4$ mA	GND		0.4	v
l _{os}	Output Short Circuit Current	$V_{OUT} = 0V$		-39		mA
l _{oz}	TRI-STATE® Output Current	PDB = 0V, V _{OUT} = 0V or V _{DD}	-20	±1	+20	μA
LVCMOS	DC SPECIFICATIONS 1.8V I/C	O (SER INPUTS, DES OUTPUTS, CO	NTROL INPUTS AND	OUTPUTS	S)	
V _{IH}	High Level Input Voltage	V _{IN} = 1.71V to 1.89V	0.65 V _{IN}		V _{IN} +0.3	v
V _{IL}	Low Level Input Voltage	V _{IN} = 1.71V to 1.89V	GND		0.35 V _{IN}	v
I _{IN}	Input Current	V _{IN} = 0V or 1.89V V _{IN} = 1.71V to 1.89V	-20	±1	+20	μA

Symbol	Parameter	Conditio	ns	Min	Тур	Max	Units	
V _{OH}	High Level Output Voltage	V _{DDIO} = 1.71V to 1.89V I _{OH} = -4 mA	V _{DDIO} - 0.45		V _{DDIO}	۷		
V _{OL}	Low Level Output Voltage	$V_{DDIO} = 1.71V \text{ to } 1.89V$ $I_{OL} = +4 \text{ mA}$	GND		0.45	V		
I _{os}	Output Short Circuit Current	$V_{OUT} = 0V$			-20		mA	
I _{oz}		$PDB = 0V,$ $V_{OUT} = 0V \text{ or } V_{DD}$		-20	±1	+20	μA	
	/ER DC SPECIFICATIONS (DO	OUT+, DOUT-)						
IV _{OD} I	Output Differential Voltage	R _T = 100Ω (<i>Figure 7</i>)		268	340	412	mV	
ΔV _{OD}	Output Differential Voltage Unbalance	R _L = 100Ω			1	50	mV	
V _{os}	Output Differential Offset Voltage	R _L = 100Ω (<i>Figure 7</i>)		V _{DD (MIN)} - V _{OD (MAX)}	V _{DD} - V _{OD}	V _{DD (MAX)} - V _{OD (MIN)}	V	
ΔV _{os}	Offset Voltage Unbalance	$R_L = 100\Omega$			1	50	mV	
I _{OS}	Output Short Circuit Current	DOUT+/- = 0V			-27		mA	
R _T	Differential Internal Termination Resistance	Differential across DOUT+	80	100	120	Ω		
CML REC	EIVER DC SPECIFICATIONS	(RIN+, RIN-)		ļ	1			
V _{TH}	Differential Threshold High Voltage	(Figure 8)			+90	m\/		
V _{TL}	Differential Threshold Low Voltage			-90			- mV	
V _{IN}	Differential Input Voltage Range	RIN+ - RIN-		180			mV	
I _{IN}	Input Current	$V_{IN} = V_{DD} \text{ or } 0V,$ $V_{DD} = 1.89V$		-20	±1	+20	μA	
R _T	Differential Internal Termination Resistance	Differential across RIN+ and RIN-		80	100	120	Ω	
SER/DES	SUPPLY CURRENT *DIGITAL	., PLL, AND ANALOG VDD)					
I _{DDT}	Serializer (Tx) VDDn Supply Current (includes load current)	$R_T = 100\Omega$ WORST CASE pattern (<i>Figure 5</i>)	VDDn = 1.89V PCLK = 43 MHz Default Registers		62	90	mA	
		$R_T = 100\Omega$ RANDOM PRBS-7 pattern			55			
I _{DDIOT}	Serializer (Tx) VDDIO Supply Current (includes load current)	$R_T = 100\Omega$ WORST CASE pattern (<i>Figure 5</i>)	VDDIO = 1.89V PCLK = 43 MHz Default Registers		2	5	1	
			VDDIO = 3.6V PCLK = 43 MHz Default Registers		7	15	mA	
I _{DDTZ}	Serializer (Tx) Supply Current		V _{DDn} = 1.89V		370	775		
I _{DDIOTZ}	Power-down	LVCMOS Inputs = 0V	V _{DDIO} = 1.89V		55	125	μA	
			V _{DDIO} = 3.6V		65	135		

Symbol	Parameter	Condition	ns	Min	Тур	Max	Units
I _{DDR}	Deserializer (Rx) VDDn Supply Current (includes load current)	$V_{DDn} = 1.89V$ $C_L = 8 pF$ WORST CASE Pattern (<i>Figure 5</i>)	PCLK = 43 MHz SSCG[3:0] = ON Default Registers		60	96	
		$V_{DDn} = 1.89V$ $C_L = 8 pF$ RANDOM PRBS-7 Pattern	PCLK = 43 MHz Default Registers		53		mA
I _{DDIOR}	Deserializer (Rx) VDDIO Supply Current (includes load current)	$V_{DDIO} = 1.89V$ $C_L = 8 pF$ WORST CASE Pattern (<i>Figure 5</i>)	PCLK = 43 MHz Default Registers		21	32	
		$V_{DDIO} = 3.6V$ $C_L = 8 \text{ pF}$ WORST CASE Pattern	PCLK = 43 MHz Default Registers		49	83	
I _{DDRZ}	Deserializer (Rx) Supply	PDB = 0V; All other	V _{DDn} = 1.89V		42	400	
IDDIORZ	Current Power-down	LVCMOS Inputs = 0V	V _{DDIO} = 1.89V		8	40	μA
			$V_{DDIO} = 3.6V$		350	800	

Recommended Serializer Timing for PCLK (*Note 12*) Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{TCP}	Transmit Clock Period	10 MHz – 43 MHz	23.3	Т	100	ns
t _{TCIH}	Transmit Clock Input High Time		0.4T	0.5T	0.6T	ns
t _{TCIL}	Transmit Clock Input Low Time		0.4T	0.5T	0.6T	ns
t _{CLKT}	PCLK Input Transition Time (<i>Figure 9</i>)		0.5		3	ns
f _{osc}	Internal oscillator clock source			25		MHz

DS90UR903Q/DS90UR904Q

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{LHT}	CML Low-to-High Transition Time	R _L = 100Ω (<i>Figure 6</i>)		150	330	ps
t _{HLT}	CML High-to-Low Transition Time	$R_L = 100\Omega \ (Figure \ 6)$		150	330	ps
t _{DIS}	Data Input Setup to PCLK	Serializer Data Inputs	2.0			ns
t _{DIH}	Data Input Hold from PCLK	(Figure 10)	2.0			ns
t _{PLD}	Serializer PLL Lock Time	R _L = 100Ω (<i>Note 5</i> , <i>Note 11</i>)		1	2	ms
t _{SD}	Serializer Delay	$R_{T} = 100\Omega$ PCLK = 10–43 MHz Register 0x03h b[0] (TRFB = 1) (<i>Figure 12</i>)	6.386T + 5	6.386T + 12	6.386T + 19.7	ns
t _{JIND}	Serializer Output Deterministic Jitter	Serializer output intrinsic deterministic jitter . Measured (cycle-cycle) with PRBS-7 test pattern PCLK = 43 MHz (<i>Note 4, Note 13</i>)		0.13		UI
t _{JINR}	Serializer Output Random Jitter	Serializer output intrinsic random jitter (cycle-cycle). Alternating-1,0 pattern. PCLK = 43 MHz (<i>Note 4, Note 13</i>)		0.04		UI
t _{JINT}	Peak-to-peak Serializer Output Jitter	Serializer output peak-to-peak jitter includes deterministic jitter, random jitter, and jitter transfer from serializer input. Measured (cycle-cycle) with PRBS-7 test pattern. PCLK = 43 MHz (<i>Note 4, Note 13</i>)		0.396		UI
λ _{STXBW}	Serializer Jitter Transfer Function -3 dB Bandwidth	PCLK = 43 MHz Default Registers (<i>Figure 18</i>) (<i>Note 4</i>)		1.90		MHz
δ _{STX}	Serializer Jitter Transfer Function (Peaking)	PCLK = 43 MHz Default Registers (<i>Figure 18</i>) (<i>Note 4</i>)		0.944		dB
δ _{STXf}	Serializer Jitter Transfer Function (Peaking Frequency)	PCLK = 43 MHz Default Registers (<i>Figure 18</i>) (<i>Note 4</i>)		500		kHz

ſ

t_{ROH}

t_{DD}

t_{DDLT}

t_{RJIT}

t_{RCJ}

t_{DPJ}

t_{DCCJ}

fdev

fmod

Jitter

	Dese	rializer Switching Ch	aracteristics			
2	Over rec	commended operating supply and t	emperature ranges unless	otherwise specified.		_
200	Symbol	Parameter	Conditions	Pin/Freq.	Min	
š	t _{RCP}	Receiver Output Clock Period	$t_{RCP} = t_{TCP}$	PCLK	23.3	
5	t _{PDC}	PCLK Duty Cycle	Default Registers SSCG[3:0] = OFF	PCLK	45	
	t _{CLH}	LVCMOS Low-to-High Transition Time	V _{DDIO} : 1.71V to 1.89V or 3.0 to 3.6V,	PCLK	1.3	
DRC D	t _{CHL}	LVCMOS High-to-Low Transition Time	C _L = 8 pF (lumped load) Default Registers (<i>Figure 14</i>) (<i>Note 10</i>)		1.3	
	t _{CLH}	LVCMOS Low-to-High Transition Time	V _{DDIO} : 1.71V to 1.89V or 3.0 to 3.6V,	Deserializer ROUTn Data Outputs	1.6	
	t _{CHL}	LVCMOS High-to-Low Transition Time	C _L = 8 pF (lumped load) Default Registers (<i>Figure 14</i>) (<i>Note 10</i>)		1.6	
	t _{ROS}	ROUT Setup Data to PCLK	V _{DDIO} : 1.71V to 1.89V or	Deserializer ROUTn	0.38T	

3.0V to 3.6V,

(RRFB = 1)

(Figure 15)

PCLK

PCLK

Default Registers Default Registers

Register 0x03h b[0]

(Figure 13) (Note 5)

(Note 13, Note 14)

SSCG[3:0] = OFF

(Note 6, Note 10)

SSCG[3:0] = OFF

(Note 7, Note 10)

SSCG[3:0] = OFF

(Note 8, Note 10) LVCMOS Output Bus

SSC[3:0] = ON

(Figure 20)

(Figure 17, Figure 19)

 $C_1 = 8 \text{ pF}$ (lumped load)

Тур

Т

50

2.0

2.0

2.4

2.4

0.5T

0.5T

4.571T

+ 12

0.53

300

120

425

320

320

300

±0.5% to

±2.0%

9 kHz to

66 kHz

0.38T

4.571T

+ 8

Data Outputs

10 MHz-43 MHz

10 MHz-43 MHz

43 MHz

10 MHz

43 MHz

10 MHz

43 MHz

10 MHz

43 MHz

20 MHz-43 MHz

20 MHz-43 MHz

Max

100

55

2.8

2.8

3.3

3.3

4.571T

+ 16

10

550

250

600

480

500

500

Units

ns

%

ns

ns

ns

ns

ms

UI

ps

ps

ps

%

kHz

ROUT Hold Data to PCLK

Deserializer Data Lock Time

Receiver Input Jitter Tolerance

Deserializer Delay

Receiver Clock Jitter

Deserializer Period Jitter

Spread Spectrum Clocking

Spread Spectrum Clocking

Deviation Frequency

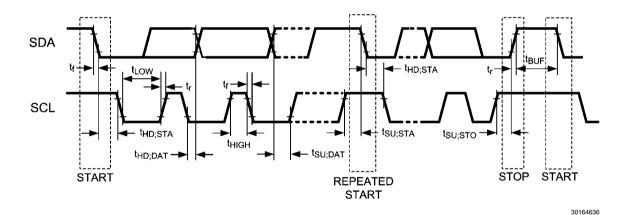
Modulation Frequency

Deserializer Cycle-to-Cycle Clock PCLK

Serial Control Bus AC Timing Specifications (SCL, SDA) - I²C Compliant (*Figure 4*)

Over recommended supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
RECOMM	IENDED INPUT TIMING REQUIREMEN	TS (Note 12)			-	
f _{SCL}	SCL Clock Frequency		>0		100	kHz
t _{LOW}	SCL Low Period	f _{SCL} = 100 kHz	4.7			μs
t _{HIGH}	SCL High Period		4.0			μs
t _{HD:STA}	Hold time for a start or a repeated start condition		4.0			μs
t _{SU:STA}	Set Up time for a start or a repeated start condition		4.7			μs
t _{HD:DAT}	Data Hold Time		0		3.45	μs
t _{SU:DAT}	Data Set Up Time		250			ns
t _{su:sto}	Set Up Time for STOP Condition		4.0			μs
t _r	SCL & SDA Rise Time				1000	ns
t _f	SCL & SDA Fall Time				300	ns
C _b	Capacitive load for bus				400	pF
SWITCHI	NG CHARACTERISTICS (Note 11)	-				
t _{HD:DAT}	Data Hold Time		0		3.45	μs
t _{SU:DAT}	Data Set Up Time		250			ns
t _f	SCL & SDA Fall Time				300	ns





Serial Control Bus DC Characteristics (SCL, SDA) - I²C Compliant

Over recommended supply	and temperature rand	aes unless otherwise	specified.
	and temperature rang	900 unicoo ounoi moo	opcomea.

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
V _{IH} Input High Level		SDA and SCL	0.7 x V _{DDIO}		V _{DDIO}	v	
V _{IL}	Input Low Level Voltage	SDA and SCL	GND		0.3 x V _{DDIO}	v	
V _{HY}	Input Hysteresis	SDA and SCL		>50		mV	
I _{OZ}	TRI-STATE Output Current	PDB = 0V V _{OUT} = 0V or V _{DD}	-20	±1	+20	μΑ	
I _{IN}	Input Current	SDA or SCL, Vin = V _{DDIO} or GND	-20	±1	+20	μA	

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
C _{IN}	Input Pin Capacitance			<5		pF	
V _{OL}	Low Level Output Voltage	SCL and SDA $V_{DDIO} = 3.0V$ $I_{OL} = 1.5mA$			0.36	V	
		SCL and SDA $V_{DDIO} = 1.71V$ $I_{OL} = 1mA$			0.36	v	

Note 1: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional; the device should not be operated beyond such conditions.

Note 2: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 3: Current into device pins is defined as positive. Current out of a device pin is defined as negative. Voltages are referenced to ground except VOD, ΔVOD, VTH and VTL which are differential voltages.

Note 4: Typical values represent most likely parametric norms at 1.8V or 3.3V, $T_A = +25^{\circ}C$, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 5: t_{PLD} and t_{DDLT} is the time required by the serializer and deserializer to obtain lock when exiting power-down state with an active PCLK

Note 6: t_{DCI} is the maximum amount of jitter measured over 30,000 samples based on Time Interval Error (TIE).

Note 7: t_{DPJ} is the maximum amount the period is allowed to deviate measured over 30,000 samples.

Note 8: t_{DCC.1} is the maximum amount of jitter between adjacent clock cycles measured over 30,000 samples.

Note 9: Supply noise testing was done with minimum capacitors (as shown on Figures 27, 28) on the PCB. A sinusoidal signal is AC coupled to the VDDn (1.8V) supply with amplitude = 25 mVp-p measured at the device VDDn pins. Bit error rate testing of input to the Ser and output of the Des with 10 meter cable shows no error when the noise frequency on the Ser is less than 1 MHz. The Des on the other hand shows no error when the noise frequency is less than 750 kHz.

Note 10: Specification is guaranteed by characterization and is not tested in production.

Note 11: Specification is guaranteed by design.

Note 12: Recommended Input Timing Requirements are input specifications and not tested in production.

Note 13: UI – Unit Interval is equivalent to one ideal serialized data bit width. The UI scales with PCLK frequency.

Note 14: t_{RJIT} max (0.61UI) is limited by instrumentation and actual t_{RJIT} of in-band jitter at low frequency (<2 MHz) is greater 1 UI.

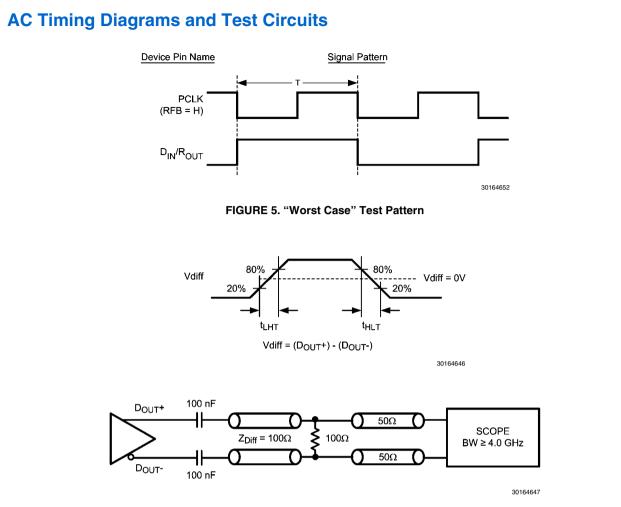
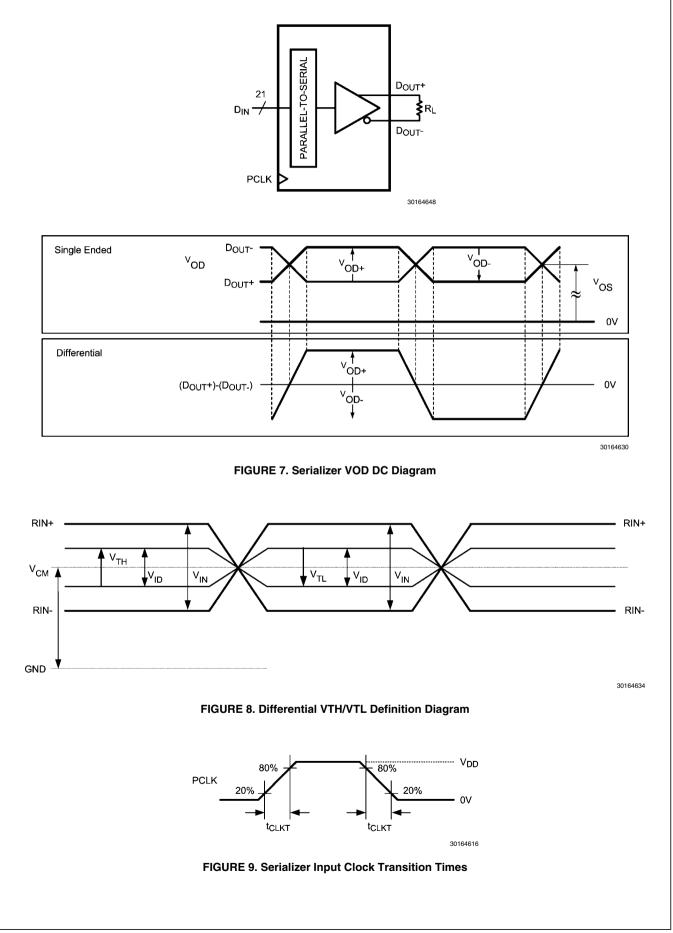


FIGURE 6. Serializer CML Output Load and Transition Times



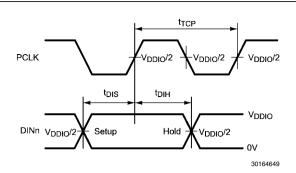
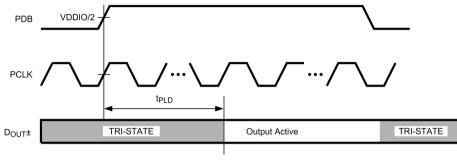


FIGURE 10. Serializer Setup/Hold Times



30164632

FIGURE 11. Serializer Data Lock Time

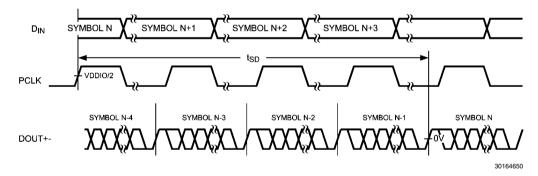
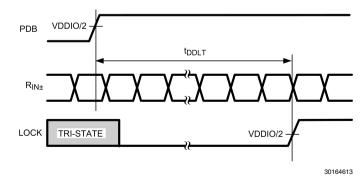
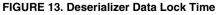
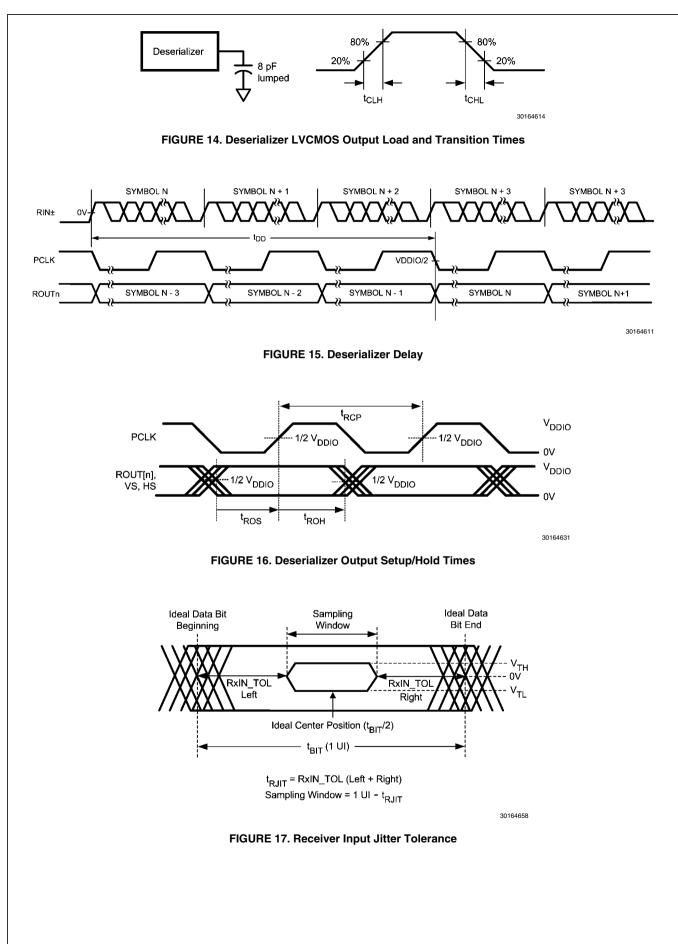


FIGURE 12. Serializer Delay







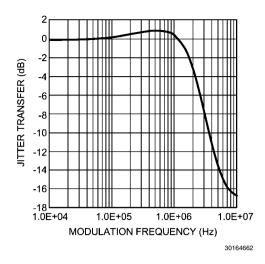


FIGURE 18. Typical Serializer Jitter Transfer Function Curve at 43 MHz

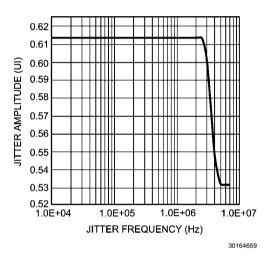
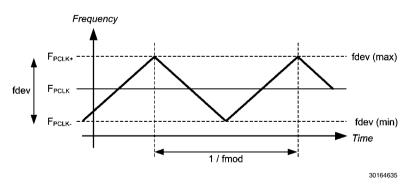


FIGURE 19. Typical Deserializer Input Jitter Tolerance Curve at 43 MHz





Addr (Hex)	Name	Bits	Field	R/W	Default	Description
(nex)						7-bit address of Serializer; 0x58'h
0	I ² C Device ID	7:1	DEVICE ID		OvDOlh	(1011_000X'b) default
0	I ² C Device ID	0	SER ID SEL	RW	0xB0'h	0: Device ID is from ID[x]
						1: Register I ² C Device ID overrides ID[x]
		7:3	RESERVED		0x00'h	Reserved
		2	RESERVED	RW	0	Reserved
1	Reset	1	DIGITAL RESET0	RW	0 self clear	1: Resets the device to default register values. Does no affect device I ² C Bus or Device ID
					0	1: Digital Reset, retains all register values
		0	DIGITAL RESET1	RW	self clear	
2	Reserved	7:0	RESERVED		0x20'h	Reserved
	Reserved	7:6	RESERVED		11'b	Reserved
						Auto V _{DDIO} detect
	VDDIO Control	5	VDDIO CONTOL	RW	1	Allows manual setting of VDDIO by register.
	VDDIO CONIIO					0: Disable
						1: Enable (auto detect mode)
						VDDIO voltage set
	VDDIO Mode	4	VDDIO MODE	RW	1	Only used when VDDIOCONTROL = 0 0: 1.8V
						1: 3.3V
•	RESERVED	3	RESERVED	RW	1	Reserved
3	RESERVED	2	RESERVED		0	Reserved
						Switch over to internal 25 MHz Oscillator clock in the
	PCLK_AUTO	1	PCLK_AUTO	RW	1	absence of PCLK
						0: Disable
						1: Enable
						Pixel Clock Edge Select: 0: Parallel Interface Data is strobed on the Falling Cloc
	TRFB	0	TRFB	RW	1	Edge.
		-				1: Parallel Interface Data is strobed on the Rising Clock
						Edge.
4	Reserved	7:0	RESERVED		0x80'h	Reserved
5	Reserved	7:0	RESERVED	RW	0x40'h	Reserved
6	Reserved	7:0	RESERVED	RW	0xC0'h	Reserved
7	Reserved	7:0	RESERVED	RW	0x00'h	Reserved
8	Reserved	7:0	RESERVED		0x00'h	Reserved
9	Reserved	7:0	RESERVED		0x01'h	
<u>A</u>	Reserved	7:0	RESERVED		0x00'h	Reserved
В	Reserved	7:0	RESERVED		0x00'h	Reserved
	Reserved	7:3	RESERVED		0x00'h	Reserved
С	PCLK Detect	2	PCLK DETECT	R	0	1: Valid PCLK detected 0: Valid PCLK not detected
0	Reserved	3	RESERVED		0	Reserved
	Reserved	0	RESERVED	R	0	Reserved
D	Reserved	7:0	RESERVED		0x11'h	Reserved
Е	Reserved	7:0	RESERVED		0x01'h	Reserved
F	Reserved	7:0	RESERVED		0x03'h	Reserved
10	Reserved	7:0	RESERVED		0x03'h	Reserved
11	Reserved	7:0	RESERVED		0x03'h	Reserved

Addr (Hex)	Name	Bits	Field	R/W	Default	Description		
12	Reserved	7:0	RESERVED		0x03'h	Reserved		
				GPCR[7]			0: LOW	
			GPCR[6]			1: HIGH		
			GPCR[5]					
13	General Purpose	7:0	GPCR[4]	RW	0x00'h			
13	Control Reg	7.0	GPCR[3]		0x0011			
			GPCR[2]					
			GPCR[1]					
			GPCR[0]					

ſ

Addr (Hex)	Name	Bits	Field	R/W	Default	Description
0	I ² C Device ID	7:1	DEVICE ID	RW	0xC0'h	7-bit address of Deserializer; 0x60h (1100_000X) default
		0	DES ID SEL			0: Device ID is from ID[x] 1: Register I ² C Device ID overrides ID[x]
		7:3	RESERVED		0x00'h	Reserved
		2	RESERVED	RW	0	Reserved
1	Reset	1	DIGITALRESET0	RW	0 self clear	1: Resets the device to default register values. Does no affect device I ² C Bus or Device ID
		0	DIGITALRESET1	RW	0 self clear	1: Digital Reset, retains all register values
	RESERVED	7:6	RESERVED		00'b	Reserved
	Auto Clock	5	AUTO_CLOCK	RW	0	1: Output PCLK or Internal 25 MHz Oscillator clock 0: Only PCLK when valid PCLK present
	OSS Select	4	OSS_SEL	RW	0	Output Sleep State Select 0: Outputs = TRI-STATE, when LOCK = L 1: Outputs = LOW , when LOCK = L
2	SSCG	3:0	SSCG		0000'b	SSCG Select 0000: Normal Operation, SSCG OFF (default) 0001: fmod (kHz) PCLK/2168, fdev ±0.50% 0010: fmod (kHz) PCLK/2168, fdev ±1.00% 0011: fmod (kHz) PCLK/2168, fdev ±1.50% 0100: fmod (kHz) PCLK/2168, fdev ±0.50% 0101: fmod (kHz) PCLK/1300, fdev ±0.50% 0110: fmod (kHz) PCLK/1300, fdev ±1.00% 0111: fmod (kHz) PCLK/1300, fdev ±2.00% 1000: fmod (kHz) PCLK/1300, fdev ±0.50% 1001: fmod (kHz) PCLK/868, fdev ±0.50% 1010: fmod (kHz) PCLK/868, fdev ±1.00% 1011: fmod (kHz) PCLK/868, fdev ±1.50% 1100: fmod (kHz) PCLK/650, fdev ±0.50% 1101: fmod (kHz) PCLK/650, fdev ±0.50% 1111: fmod (kHz) PCLK/650, fdev ±1.50%
	RESERVED	7:6	RESERVED		11'b	Reserved
	VDDIO Control	5	VDDIO CONTROL	RW	1	Auto voltage control 0: Disable 1: Enable (auto detect mode)
	VDDIO Mode	4	VDDIO MODE	RW	0	VDDIO voltage set 0: 1.8V 1: 3.3V
3	RESERVED	3	RESERVED	RW	1	Reserved
	RESERVED	2	RESERVED	RW	0	Reserved
	RESERVED	1	RESERVED		0	Reserved
	RRFB	0	RRFB	RW	1	Pixel Clock Edge Select 0: Parallel Interface Data is strobed on the Falling Clock Edge 1: Parallel Interface Data is strobed on the Rising Clock Edge.

Addr (Hex)	Name	Bits	Field	R/W	Default	Description
4	EQ Control	7:0	EQ	RW	0x00'h	EQ Gain 00'h = ~0.0 dB 01'h = ~4.5 dB 03'h = ~6.5 dB 07'h = ~7.5 dB 0F'h = ~8.0 dB 1F'h = ~11.0 dB 3F'h = ~12.5 dB FF'h = ~14.0 dB
5	RESERVED	7:0	RESERVED		0x00'h	Reserved
	RESERVED	7	RESERVED		0	Reserved
6	RESERVED	6:4	RESERVED	RW	000'b	Reserved
	RESERVED	3:0	RESERVED	RW	1111'b	Reserved
7	RESERVED	7:0	RESERVED	RW	0xB0'h	Reserved
8:17	RESERVED	7:0	RESERVED	RW	0x00'h	Reserved
18	RESERVED	7:0	RESERVED		0x00'h	Reserved
19	RESERVED	7:0	RESERVED		0x01'h	Reserved
1A	RESERVED	7:0	RESERVED		0x00'h	Reserved
1B	RESERVED	7:0	RESERVED		0x00'h	Reserved
	RESERVED	7:3	RESERVED		0x00'h	Reserved
	RESERVED	2	RESERVED		0	Reserved
1C	Signal Detect Status	1		R	0	0: Active signal not detected 1: Active signal detected
	LOCK Pin Status	0		R	0	0: CDR/PLL Unlocked 1: CDR/PLL Locked
1D	Reserved	7:0	RESERVED		0x17'h	Reserved
1E	Reserved	7:0	RESERVED		0x07'h	Reserved
1F	Reserved	7:0	RESERVED		0x01'h	Reserved
20	Reserved	7:0	RESERVED		0x01'h	Reserved
21	Reserved	7:0	RESERVED		0x01'h	Reserved
22	Reserved	7:0	RESERVED		0x01'h	Reserved
23	General Purpose Control Reg	7:0	GPCR[7] GPCR[6] GPCR[5] GPCR[4] GPCR[3] GPCR[2] GPCR[1] GPCR[0]	RW	0x00'h	0: LOW 1: HIGH
24	RESERVED	0	RESERVED	RW	0	Reserved
25	RESERVED	7:0	RESERVED	R	0x00'h	Reserved
26		7:6	RESERVED	RW	00'b	Reserved
26	RESERVED	5:0	RESERVED	RW	0	Reserved

Functional Description

The DS90UR903Q/904Q FPD-Link II chipset is intended for video display applications. The Serializer/ Deserializer chipset operates from a 10 MHz to 43 MHz pixel clock frequency. The DS90UR903Q transforms a 21-bit wide parallel LVCMOS data bus into a single high-speed differential pair. The high-speed serial bit stream contains an embedded clock and DC-balance information which enhances signal quality to support AC coupling. The DS90UR904Q receives the single serial data stream and converts it back into a 21-bit wide parallel data bus.

DISPLAY APPLICATION

The DS90UR903Q/904Q chipset is intended for interface between a host (graphics processor) and a Display. It supports a 21 bit parallel video bus for 18-bit color depth (RGB666) display format. In a RGB666 configuration, 18 color bits (R [5:0], G[5:0], B[5:0]), Pixel Clock (PCLK) and three control bits (VS, HS and DE) are supported across the serial link.

The DS90UR903Q Serializer accepts a 21-bit parallel data bus. The parallel data is converted into a single differential link. The DS90UR904Q Deserializer extracts the clock/control information from the incoming data stream and reconstructs the 21-bit parallel data.

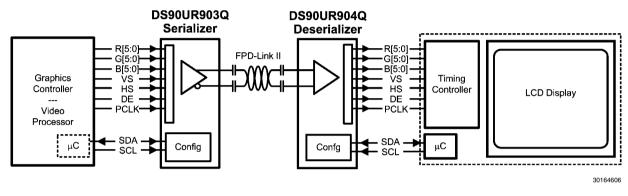
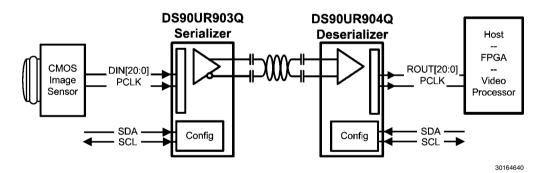


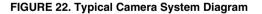
FIGURE 21. Typical Display System Diagram

CAMERA APPLICATION

Camera applications are also supported by the DS90UR903Q/904Q chipset. The host controller/processsor

is connected to the deserializer, while the CMOS image sensor provides data to the serializer.





SERIAL FRAME FORMAT

The DS90UR903Q/904Q chipset will transmit and receive a pixel of data in the following format:

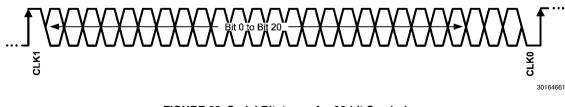


FIGURE 23. Serial Bitstream for 28-bit Symbol

The High Speed Serial Channel is a 28-bit symbol composed of 21 bits of data containing video data & control information transmitted from Serializer to Deserializer. CLK1 and CLK0 represent the embedded clock in the serial stream. CLK1 is always HIGH and CLK0 is always LOW. This data payload is optimized for signal transmission over an AC coupled link. Data is randomized, balanced and scrambled.

DESCRIPTION OF SERIAL CONTROL BUS

ID[X] ADDRESS DECODER

The ID[x] pin is used to decode and set the physical slave address of the Serializer/Deserializer (I²C only) to allow up to

six devices on the bus using only a single pin. The pin sets one of six possible addresses for each Serializer/Deserializer device. The pin must be pulled to VDD (1.8V, NOT VDDIO)) with a 10 k Ω resistor and a pull down resistor (RID) of the recommended value to set the physical device address. The recommended maximum resistor tolerance is 0.1% worst case (0.2% total tolerance).

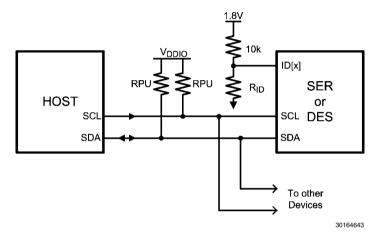


FIGURE 24. Serial Control Bus Connection

TABLE 3. ID[x] Resistor Value – DS90UR903Q

ID[x] Resistor Value - DS90UR903Q Ser				
Resistor	Address 7'b	Address 8'b 0		
RID Ω	(Note 11)	appended (WRITE)		
(±0.1%)				
0	7b' 101 1000 (h'58)	8b' 1011 0000 (h'B0)		
GND				
2.0k	7b' 101 1001 (h'59)	8b' 1011 0010 (h'B2)		
4.7k	7b' 101 1010 (h'5A)	8b' 1011 0100 (h'B4)		
8.2k	7b' 101 1011 (h'5B)	8b' 1011 0110 (h'B6)		
12.1k	7b' 101 1100 (h'5C)	8b' 1011 1000 (h'B8)		
39.0k	7b' 101 1110 (h'5E)	8b' 1011 1100 (h'BC)		

TABLE 4. ID[x] Resistor Value – DS90UR904Q

ID[x] Resistor Value - DS90UR904Q Des				
Resistor	Address 7'b	Address 8'b 0		
RID Ω	(Note 11)	appended (WRITE)		
(±0.1%)				
0	7b' 110 0000 (h'60)	8b' 1100 0000 (h'C0)		
GND				
2.0k	7b' 110 0001 (h'61)	8b' 1100 0010 (h'C2)		
4.7k	7b' 110 0010 (h'62)	8b' 1100 0100 (h'C4)		
8.2k	7b' 110 0011 (h'63)	8b' 1101 0110 (h'C6)		
12.1k	7b' 110 0100 (h'64)	8b' 1101 1000 (h'C8)		
39.0k	7b' 110 0110 (h'66)	8b' 1100 1100 (h'CC)		

PROGRAMMABLE CONTROLLER

An integrated I²C slave controller is embedded in each of the DS90UR903Q Serializer and DS90UR904Q Deserializer. It must be used to access and program the extra features embedded within the configuration registers. Refer to *Table 1* and *Table 2* for details of control registers.

LVCMOS VDDIO OPTION

 $1.8 V \mbox{ or } 3.3 V \mbox{ SER}$ Inputs and DES Outputs are user selectable to provide compatibility with 1.8 V and 3.3 V system interfaces.

POWERDOWN

The SER has a PDB input pin to ENABLE or Powerdown the device. The modes can be controlled by the host and is used to disable the Link to save power when the remote device is not operational. An auto mode is also available. In this mode, the PDB pin is tied High and the SER switches over to an internal oscillator when the PCLK stops or not present. When a PCLK starts again, the SER will then lock to the valid input PCLK and transmits the data to the DES. In powerdown mode, the high-speed driver outputs are static (High).

The DES has a PDB input pin to ENABLE or Powerdown the device. This pin can be controlled by the system and is used to disable the DES to save power. An auto mode is also available. In this mode, the PDB pin is tied High and the DES will enter powerdown when the serial stream stops. When the serial stream starts up again, the DES will lock to the input stream and assert the LOCK pin and output valid data. In powerdown mode, the Data and PCLK outputs are set by the OSS_SEL control register.

POWER UP REQUIREMENTS AND PDB PIN

It is required to delay and release the PDB input signal after VDD (VDDn and VDDIO) power supplies have settled to the recommended operating voltages. A external RC network can be connected to the PDB pin to ensure PDB arrives after all the VDD have stabilized.

SIGNAL QUALITY ENHANCERS

Des - Receiver Input Equalization (EQ)

The receiver inputs provided input equalization filter in order to compensate for loss from the media. The level of equalization is controlled via register setting.

EMI REDUCTION

Des - Receiver Staggered Output

The Receiver staggered outputs allows for outputs to switch in a random distribution of transitions within a defined window. Outputs transitions are distributed randomly. This minimizes the number of outputs switching simultaneously and helps to reduce supply noise. In addition it spreads the noise spectrum out reducing overall EMI.

Des Spread Spectrum Clocking

The DS90UR904Q parallel data and clock outputs have programmable SSCG ranges from 9 kHz–66 kHz and $\pm 0.5\%$ – $\pm 2\%$ from 20 MHz to 43 MHz. The modulation rate and modulation frequency variation of output spread is controlled through the SSC control registers.

PIXEL CLOCK EDGE SELECT (TRFB/RRFB)

The TRFB/RRFB selects which edge of the Pixel Clock is used. For the SER, this register determines the edge that the data is latched on. If TRFB register is 1, data is latched on the Rising edge of the PCLK. If TRFB register is 0, data is latched on the Falling edge of the PCLK. For the DES, this register determines the edge that the data is strobed on. If RRFB register is 1, data is strobed on the Rising edge of the PCLK. If RRFB register is 0, data is strobed on the Falling edge of the PCLK.

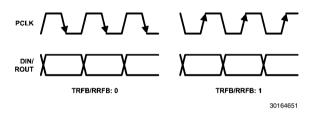


FIGURE 25. Programmable PCLK Strobe Select

Applications Information

nal AC coupling capacitors must be placed in series in the FPD-Link II signal path as illustrated in *Figure 26*.

AC COUPLING

The SER/DES supports only AC-coupled interconnects through an integrated DC balanced decoding scheme. Exter-

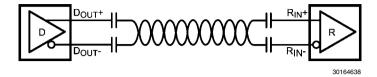


FIGURE 26. AC-Coupled Connection

For high-speed FPD-Link II transmissions, the smallest available package should be used for the AC coupling capacitor. This will help minimize degradation of signal quality due to package parasitics. The I/O's require a 100 nF AC coupling capacitors to the line.

TYPICAL APPLICATION CONNECTION

Figure 27 shows a typical connection of the DS90UR903Q Serializer.

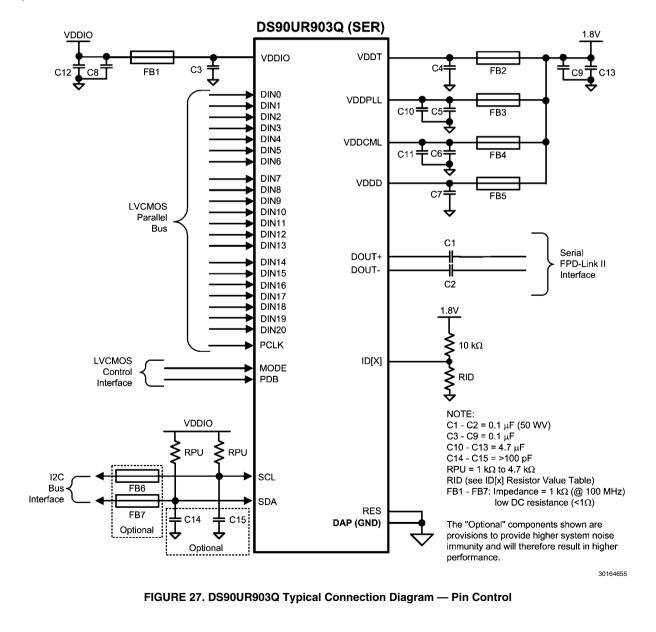
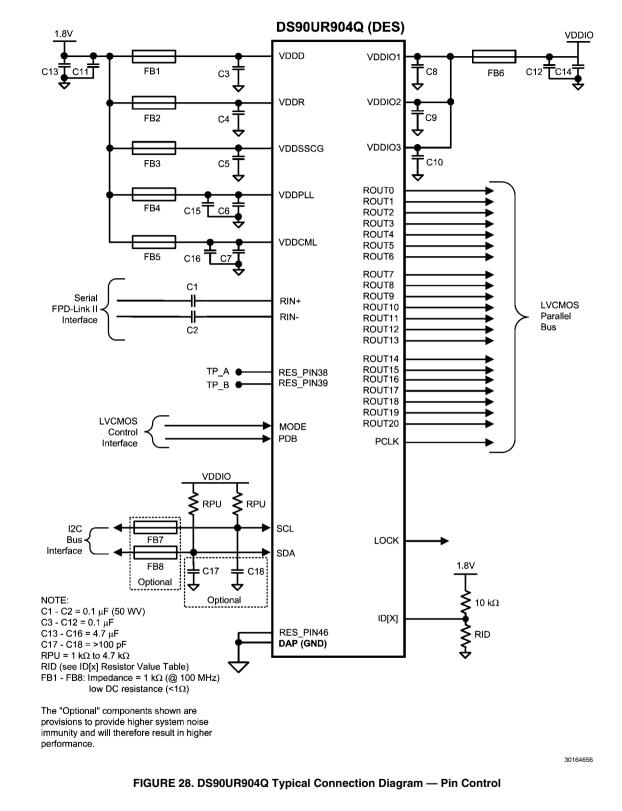


Figure 28 shows a typical connection of the DS90UR904Q Deserializer.



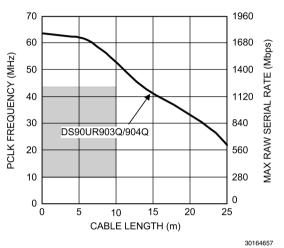
TRANSMISSION MEDIA

The Ser/Des chipset is intended to be used over a wide variety of balanced cables depending on distance and signal quality requirements. The Ser/Des employ internal termination providing a clean signaling environment. The interconnect for FPD-Link II interface should present a differential impedance of 100 Ohms. Use of cables and connectors that have matched differential impedance will minimize impedance discontinuities. Shielded or un-shielded cables may be used depending upon the noise environment and application requirements. The chipset's optimum cable drive performance is achieved at 43 MHz at 10 meters length. The maximum signaling rate increases as the cable length decreases. Therefore, the chipset supports 50 MHz at shorter distances. Other cable parameters that may limit the cable's performance boundaries are: cable attenuation, near-end crosstalk and pair-to-pair skew.

For obtaining optimal performance, we recommend:

- Use Shielded Twisted Pair (STP) cable
- 100Ω differential impedance and 24 AWG (or lower AWG) cable
- Low skew, impedance matched
- Ground and/or terminate unused conductors

Figure 29 shows the Typical Performance Characteristics demonstrating various lengths and data rates using Rosenberger HSD and Leoni DACAR 538 Cable.



*Note: Equalization is enabled for cable lengths greater than 7 meters



PCB LAYOUT AND POWER SYSTEM CONSIDERATIONS

Circuit board layout and stack-up for the Ser/Des devices should be designed to provide low-noise power feed to the device. Good layout practice will also separate high frequency or high-level inputs and outputs to minimize unwanted stray noise pickup, feedback and interference. Power system performance may be greatly improved by using thin dielectrics (2 to 4 mils) for power / ground sandwiches. This arrangement provides plane capacitance for the PCB power system with low-inductance parasitics, which has proven especially effective at high frequencies, and makes the value and placement of external bypass capacitors less critical. External bypass capacitors should include both RF ceramic and tantalum electrolytic types. RF capacitors may use values in the range of 0.01 uF to 0.1 uF. Tantalum capacitors may be in the 2.2 uF to 10 uF range. Voltage rating of the tantalum capacitors should be at least 5X the power supply voltage being used.

Surface mount capacitors are recommended due to their smaller parasitics. When using multiple capacitors per supply pin, locate the smaller value closer to the pin. A large bulk capacitor is recommend at the point of power entry. This is typically in the 50uF to 100uF range and will smooth low frequency switching noise. It is recommended to connect power and ground pins directly to the power and ground planes with bypass capacitors connected to the plane with via on both ends of the capacitor. Connecting power or ground pins to an external bypass capacitor will increase the inductance of the path.

A small body size X7R chip capacitor, such as 0603, is recommended for external bypass. Its small body size reduces the parasitic inductance of the capacitor. The user must pay attention to the resonance frequency of these external bypass capacitors, usually in the range of 20-30 MHz. To provide effective bypassing, multiple capacitors are often used to achieve low impedance between the supply rails over the frequency of interest. At high frequency, it is also a common practice to use two vias from power and ground pins to the planes, reducing the impedance at high frequency.

Some devices provide separate power for different portions of the circuit. This is done to isolate switching noise effects between different sections of the circuit. Separate planes on the PCB are typically not required. Pin Description tables typically provide guidance on which circuit blocks are connected to which power pin pairs. In some cases, an external filter many be used to provide clean power to sensitive circuits such as PLLs.

Use at least a four layer board with a power and ground plane. Locate LVCMOS signals away from the differential lines to prevent coupling from the LVCMOS lines to the differential lines. Closely-coupled differential lines of 100 Ohms are typically recommended for differential interconnect. The closely coupled lines help to ensure that coupled noise will appear as common-mode and thus is rejected by the receivers. The tightly coupled lines will also radiate less.

Information on the LLP style package is provided in National Application Note: AN-1187.

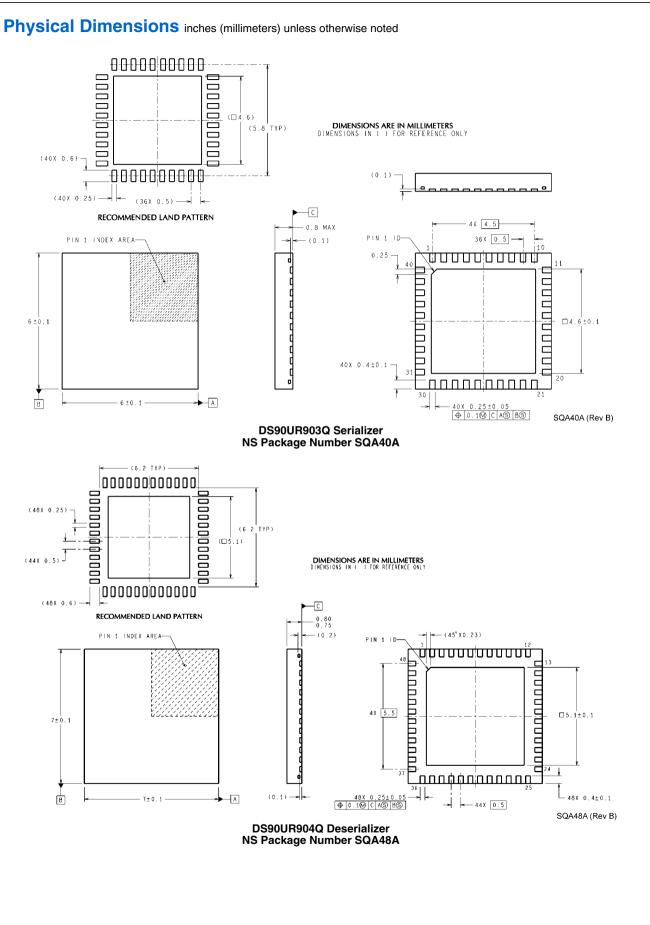
INTERCONNECT GUIDELINES

See AN-1108 and AN-905 for full details.

- Use 100Ω coupled differential pairs
- Use the S/2S/3S rule in spacings
 - -S = space between the pair
 - 2S = space between pairs
 - 3S = space to LVCMOS signal
- Minimize the number of Vias

- Use differential connectors when operating above 500Mbps line speed
- Maintain balance of the traces
- Minimize skew within the pair

Additional general guidance can be found in the LVDS Owner's Manual - available in PDF format from the National web site at: **www.national.com/lvds**



Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at: www.national.com

Products		Design Support	
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench
Audio	www.national.com/audio	App Notes	www.national.com/appnotes
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns
Data Converters	www.national.com/adc	Samples	www.national.com/samples
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic
PLL/VCO	www.national.com/wireless	PowerWise® Design University	www.national.com/training

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2011 National Semiconductor Corporation

For the most current product information visit us at www.national.com



National Semiconductor Americas Technical Support Center Email: support@nsc.com Tel: 1-800-272-9959

National Semiconductor Europe Technical Support Center Email: europe.support@nsc.com National Semiconductor Asia Pacific Technical Support Center Email: ap.support@nsc.com National Semiconductor Japan Technical Support Center Email: jpn.feedback@nsc.com